

# PS2933-1

HIGH COLLECTOR TO EMITTER VOLTAGE  
 4-PIN ULTRA SMALL FLAT-LEAD  
 PHOTOCOUPLER

R08DS0115EJ0202  
 Rev.2.02  
 Dec 8, 2021

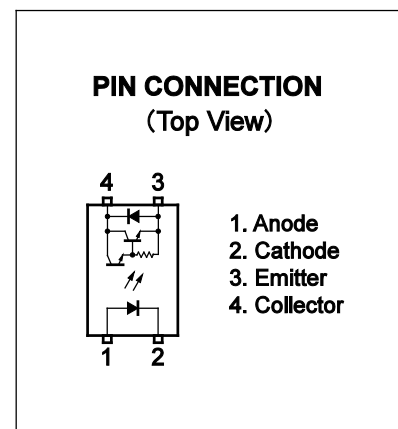
## DESCRIPTION

The PS2933-1 is an optically coupled isolator containing a GaAs light emitting diode and an NPN silicon phototransistor in one package for high density mounting applications.

An ultra small flat-lead package has been provided which realizes a reduction in mounting area of about 30% compared with the PS28xx series.

## FEATURES

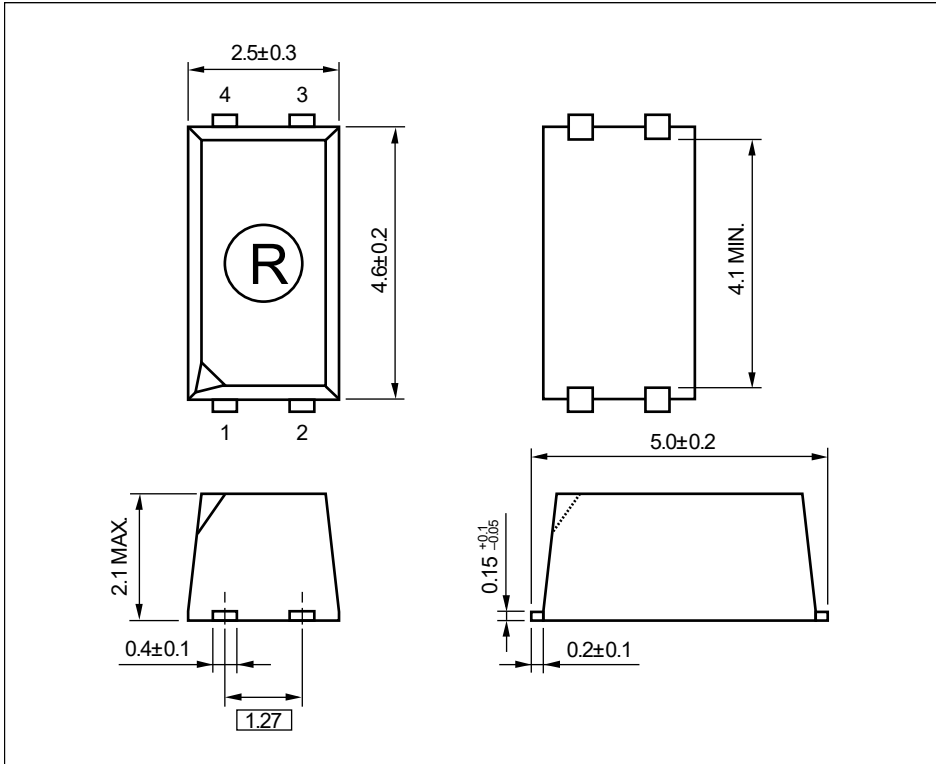
- Ultra small flat-lead package (4.6 (L) × 2.5 (W) × 2.1 (H) mm)
- High collector to emitter voltage ( $V_{CEO} = 350\text{ V}$ )
- High isolation voltage ( $BV = 2\ 500\text{ Vr.m.s.}$ )
- Ordering number of taping product: PS2933-1-F3: 3 500 pcs/reel
- Safety standards
  - UL approved: UL1577, Single protection
  - BSI approved: BS EN 62368-1, Supplementary insulation
  - VDE approved: DIN EN 60747-5-5 (Option)



## APPLICATIONS

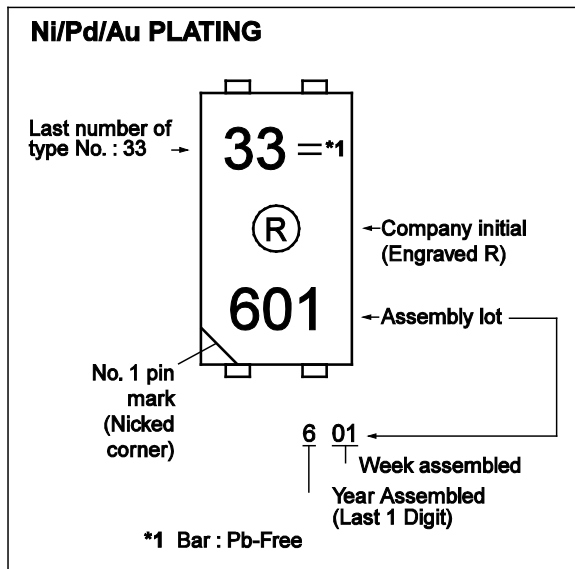
- Hybrid IC
- Telephone, Exchange equipment, FAX

**PACKAGE DIMENSIONS (UNIT: mm)**



Weight: 0.05g (typ.)

**MARKING EXAMPLE**



**PHOTOCOUPLER CONSTRUCTION**

Parameter	MIN.
Air Distance	4 mm
Creepage Distance	4 mm
Isolation Distance	0.4 mm

## ORDERING INFORMATION

Part Number	Order Number <sup>*1</sup>	Solder Plating Specification	Packing Style	Safety Standard Approval	Application Part Number <sup>*2</sup>
PS2933-1	PS2933-1-AX	Pb-Free (Ni/Pd/Au)	50 pcs (Tape 50 pcs cut)	Standard products (UL, BSI approved)	PS2933-1
PS2933-1-F3	PS2933-1-F3-AX		Embossed Tape 3 500 pcs/reel		
PS2933-1-V	PS2933-1-V-AX		50 pcs (Tape 50 pcs cut)	UL, BSI,	
PS2933-1-V-F3	PS2933-1-V-F3-AX		Embossed Tape 3 500 pcs/reel	DIN EN 60747-5-5 approved	

Note: \*1. For the application of the Safety Standard, following part number should be used.

ABSOLUTE MAXIMUM RATINGS (T<sub>A</sub> = 25 °C, unless otherwise specified)

Parameter		Symbol	Ratings	Unit
Diode	Forward Current	I <sub>F</sub>	50	mA
	Forward Current Derating	ΔI <sub>F</sub> /°C	0.5	mA/°C
	Peak Forward Current <sup>*1</sup>	I <sub>FP</sub>	0.5	A
	Power Dissipation	P <sub>D</sub>	60	mW
	Reverse Voltage	V <sub>R</sub>	6	V
Detector	Collector to Emitter Voltage	V <sub>CEO</sub>	350	V
	Emitter to Collector Voltage	V <sub>ECO</sub>	0.3	V
	Collector Current	I <sub>C</sub>	60	mA
	Power Dissipation Derating	ΔP <sub>C</sub> /°C	1.2	mW/°C
	Power Dissipation	P <sub>C</sub>	120	mW
Isolation Voltage <sup>*2</sup>		BV	2 500	V <sub>r.m.s.</sub>
Total Power Dissipation		P <sub>T</sub>	160	mW
Operating Ambient Temperature		T <sub>A</sub>	-55 to +100	°C
Storage Temperature		T <sub>stg</sub>	-55 to +150	°C

Notes: \*1. PW = 100 μs, Duty Cycle = 1 %

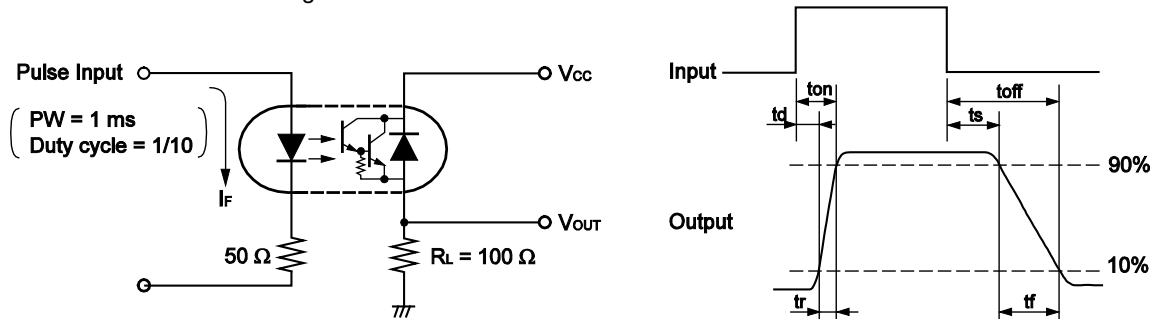
\*2. AC voltage for 1 minute at T<sub>A</sub> = 25 °C, RH = 60 % between input and output.

Pins 1-2 shorted together, 3-4 shorted together.

**ELECTRICAL CHARACTERISTICS (T<sub>A</sub> = 25 °C)**

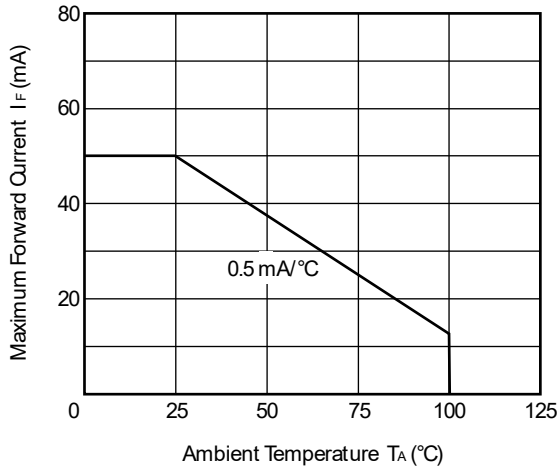
Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	V <sub>F</sub>	I <sub>F</sub> = 1 mA	0.9	1.1	1.3	V
	Reverse Current	I <sub>R</sub>	V <sub>R</sub> = 5 V			5	μA
	Terminal Capacitance	C <sub>t</sub>	V = 0 V, f = 1 MHz		15		pF
Transistor	Collector to Emitter Current	I <sub>CEO</sub>	V <sub>CE</sub> = 350V			400	nA
Coupled	Current Transfer Ratio (I <sub>C</sub> /I <sub>F</sub> )	CTR	I <sub>F</sub> = 1 mA, V <sub>CE</sub> = 2 V	400	2 000	4 500	%
	Collector Saturation Voltage	V <sub>CE(SAT)</sub>	I <sub>F</sub> = 1 mA, I <sub>C</sub> = 2 mA		0.8	1	V
	Isolation Resistance	R <sub>I-O</sub>	V <sub>I-O</sub> = 1 kV <sub>DC</sub>	10 <sup>11</sup>			Ω
	Isolation Capacitance	C <sub>I-O</sub>	V = 0 V, f = 1 MHz		0.4		pF
	Rise Time *1	t <sub>r</sub>	V <sub>CC</sub> = 5 V, I <sub>C</sub> = 10 mA, R <sub>L</sub> = 100 Ω		20		μs
Fall Time *1	t <sub>f</sub>			5			

Note: \*1. Test circuit for switching time

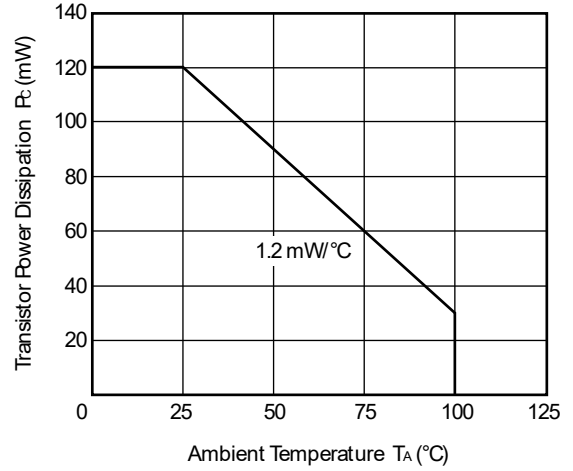


**TYPICAL CHARACTERISTICS ( $T_A = 25\text{ }^\circ\text{C}$ , unless otherwise specified)**

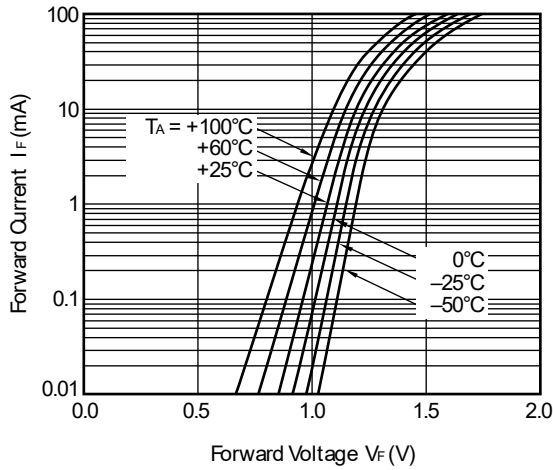
MAXIMUM FORWARD CURRENT vs. AMBIENT TEMPERATURE



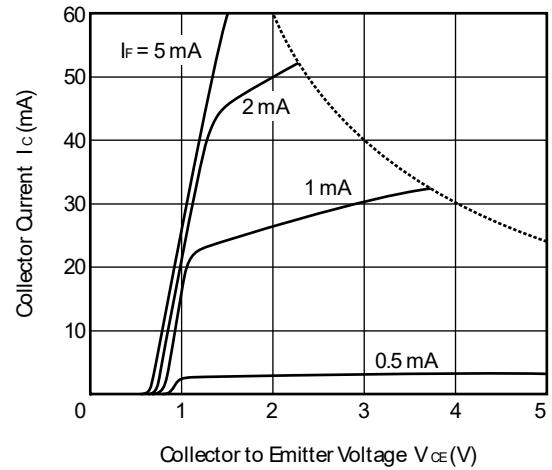
TRANSISTOR POWER DISSIPATION vs. AMBIENT TEMPERATURE



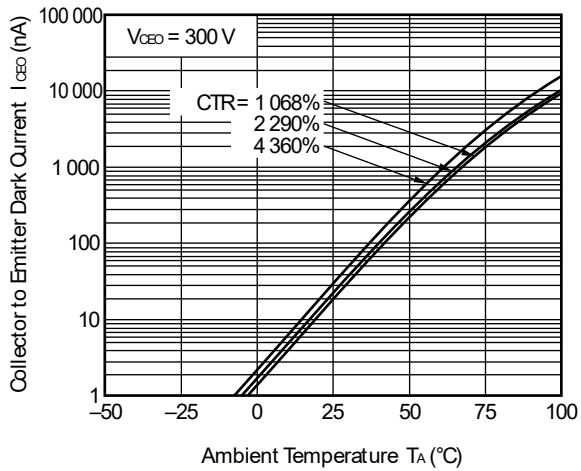
FORWARD CURRENT vs. FORWARD VOLTAGE



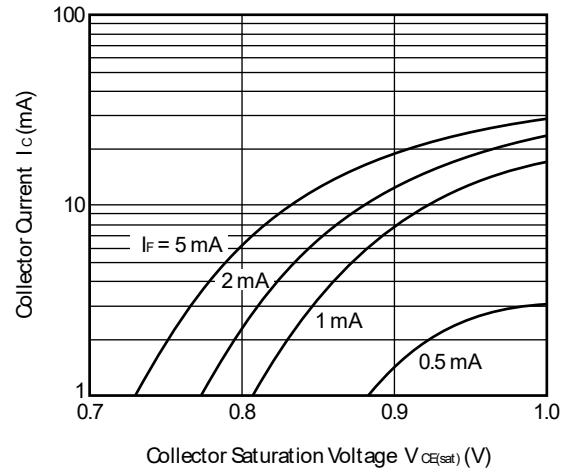
COLLECTOR CURRENT vs. COLLECTOR TO EMITTER VOLTAGE



COLLECTOR TO EMITTER DARK CURRENT vs. AMBIENT TEMPERATURE

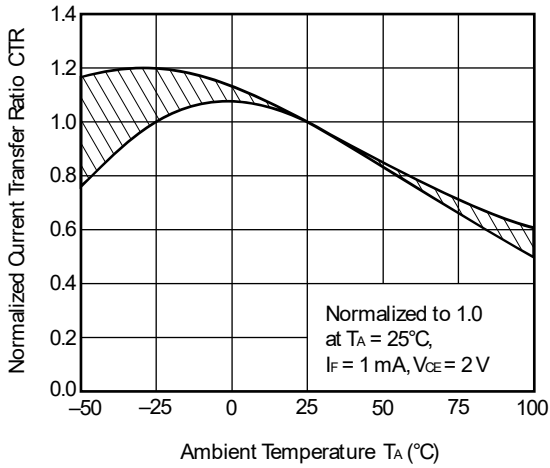


COLLECTOR CURRENT vs. COLLECTOR SATURATION VOLTAGE

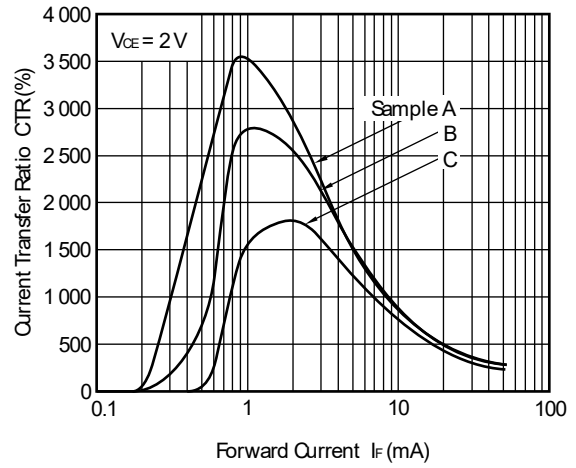


**Remark** The graphs indicate nominal characteristics.

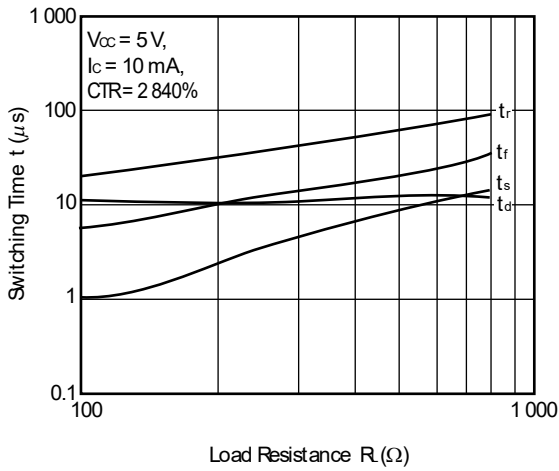
NORMALIZED CURRENT TRANSFER RATIO vs. AMBIENT TEMPERATURE



CURRENT TRANSFER RATIO vs. FORWARD CURRENT



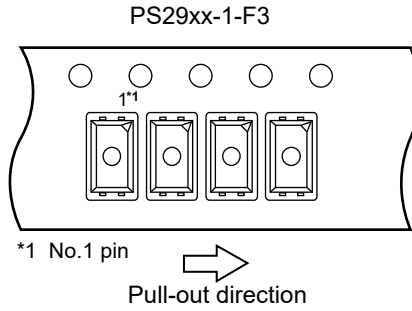
SWITCHING TIME vs. LOAD RESISTANCE



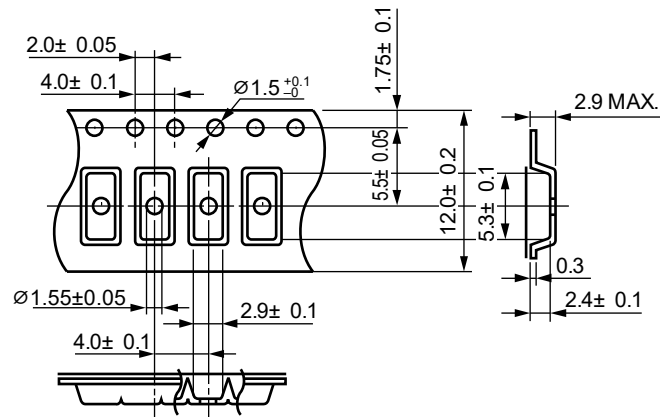
**Remark** The graphs indicate nominal characteristics.

TAPING SPECIFICATIONS (UNIT: mm)

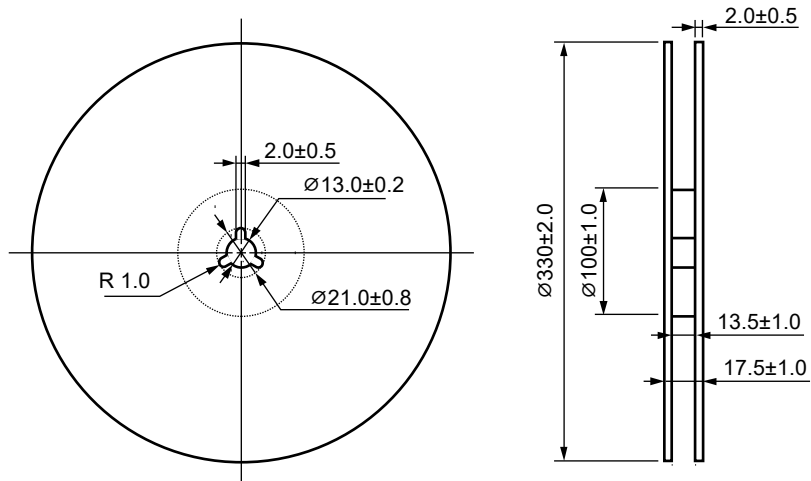
Tape Direction



Outline and Dimensions (Tape)

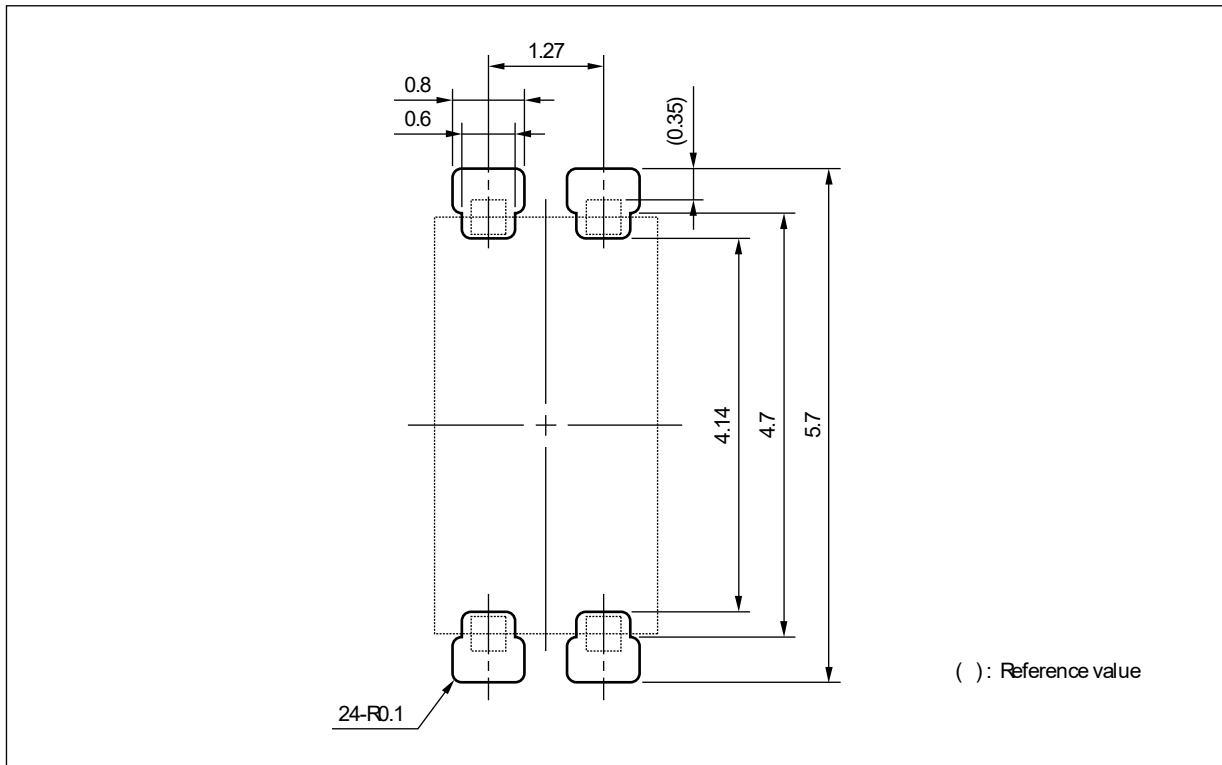


Outline and Dimensions (Reel)



Packing: 3 500 pcs/reel

## RECOMMENDED MOUNT PAD DIMENSIONS (UNIT: mm)



**Remark** This drawing is considered to meet air and outer creepage distance 4.0 mm minimum. All dimensions in this figure must be evaluated before use.



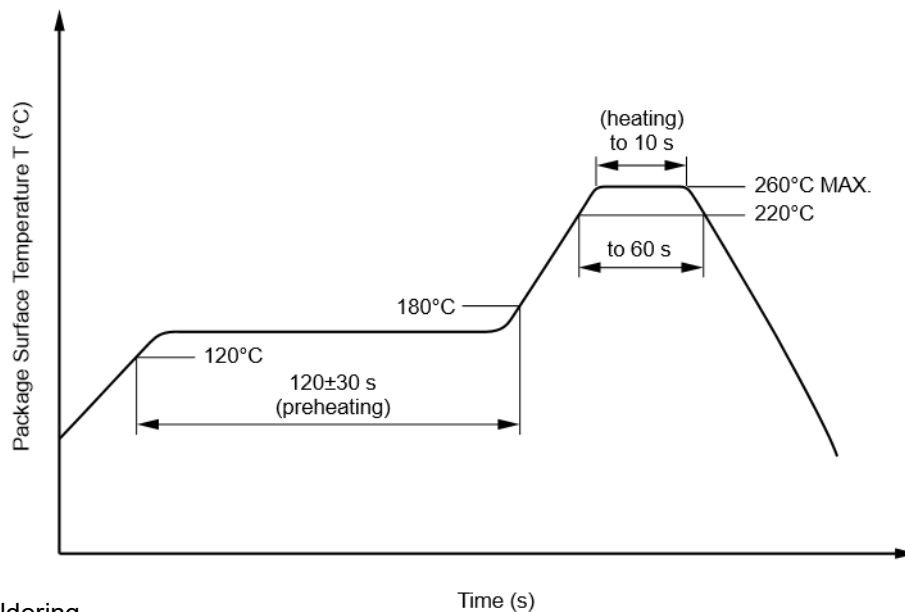
## NOTES ON HANDLING

### 1. Recommended soldering conditions

#### (1) Infrared reflow soldering

- |  |   |
|--|---|
| • Peak reflow temperature                        | 260 °C or below (package surface temperature)   |
| • Time of peak reflow temperature                | 10 seconds or less  |
| • Time of temperature higher than 220 °C         | 60 seconds or less  |
| • Time to preheat temperature from 120 to 180 °C | 120 ± 30 s  |
| • Number of reflows                              | Three   |
| • Flux   | Rosin flux containing small amount of chlorine<br>(The flux with a maximum chlorine content of 0.2 Wt% is recommended.) |

Recommended Temperature Profile of Infrared Reflow



#### (2) Wave soldering

- |                         |  |
|-------------------------|--|
| • Temperature           | 260 °C or below (molten solder temperature)  |
| • Time                  | 10 seconds or less   |
| • Preheating conditions | 120 °C or below (package surface temperature)  |
| • Number of times       | One (Allowed to be dipped in solder including plastic mold portion.)   |
| • Flux                  | Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.) |

#### (3) Soldering by Soldering Iron

- |  |   |
|--|---|
| • Peak Temperature (lead part temperature) | 350 °C or below   |
| • Time (each pins)                         | 3 seconds or less   |
| • Flux                                     | Rosin flux containing small amount of chlorine<br>(The flux with a maximum chlorine content of 0.2 Wt% is recommended.) |

(a) Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead

(b) Please be sure that the temperature of the package would not be heated over 100 °C

#### (4) Cautions

- Flux Cleaning  
Avoid cleaning with Freon based or halogen-based (chlorinated etc.) solvents.
- Do not use fixing agents or coatings containing halogen-based substances.

### 2. Cautions regarding noise

Be aware that when voltage is applied suddenly between the photocoupler's input and output or between collector-emitters at startup, the output transistor may enter the on state, even if the voltage is within the absolute maximum ratings.

3. Measurement conditions of current transfer ratios (CTR), which differ according to photocoupler  
Check the setting values before use, since the forward current conditions at CTR measurement differ according to product.

When using products other than at the specified forward current, the characteristics curves may differ from the standard curves due to CTR value variations or the like. Therefore, check the characteristics under the actual operating conditions and thoroughly take variations or the like into consideration before use.

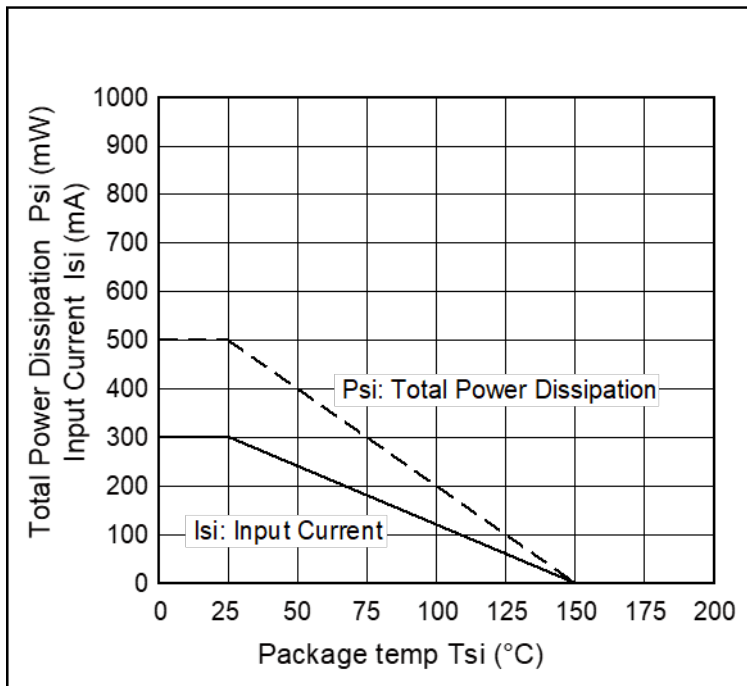
## USAGE CAUTIONS

1. Protect against static electricity when handling.
2. Avoid storage at a high temperature and high humidity.
3. Avoid cleaning with Freon based or halogen-based (chlorinated etc.) solvents.
4. Do not use fixing agents or coatings containing halogen-based substances.

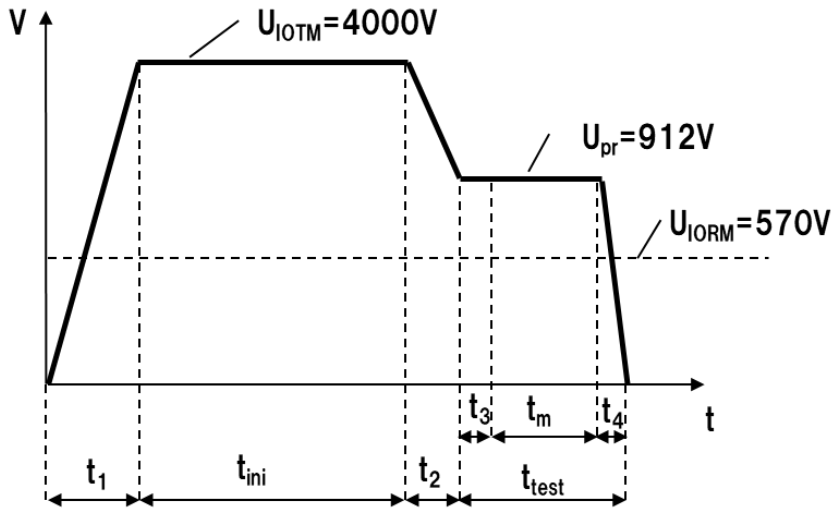
**SPECIFICATION OF VDE MARKS LICENSE DOCUMENT**

Parameter	Symbol	Rating	Unit
Climatic test class (IEC 60068-1/DIN EN 60068-1)		55/100/21	
Dielectric strength maximum operating isolation voltage Test voltage (partial discharge test, procedure a for type test and random test) $U_{pr} = 1.6 \times U_{IORM}, P_d < 5 \text{ pC}$	$U_{IORM}$ $U_{pr}$	570 912	$V_{peak}$ $V_{peak}$
Test voltage (partial discharge test, procedure b for all devices) $U_{pr} = 1.875 \times U_{IORM}, P_d < 5 \text{ pC}$	$U_{pr}$	1 068	$V_{peak}$
Highest permissible overvoltage	$U_{TR}$	4 000	$V_{peak}$
Degree of pollution (IEC 60664-1/DIN EN 60664-1 (VDE 0110-1))		2	
Comparative tracking index (IEC 60112/DIN EN 60112 (VDE 0303-11))	CTI	175	
Material group (IEC 60664-1/DIN EN 60664-1 (VDE 0110-1))		III a	
Storage temperature range	$T_{stg}$	-55 to +150	°C
Operating temperature range	$T_A$	-55 to +100	°C
Isolation resistance, minimum value $V_{IO} = 500 \text{ V dc at } T_A = 25 \text{ °C}$ $V_{IO} = 500 \text{ V dc at } T_A \text{ MAX. at least } 100 \text{ °C}$	$R_{is \text{ MIN.}}$ $R_{is \text{ MIN.}}$	$10^{12}$ $10^{11}$	$\Omega$ $\Omega$
Safety maximum ratings (maximum permissible in case of fault, see thermal derating curve) Package temperature Current (input current $I_F$ , $\Psi_i = 0$ ) Power (output or total power dissipation) Isolation resistance $V_{IO} = 500 \text{ V dc at } T_A = T_{si}$	$T_{si}$ $I_{si}$ $\Psi_{si}$ $R_{is \text{ MIN.}}$	150 300 500 $10^9$	°C mA mW $\Omega$

**Dependence of maximum safety ratings with package temperature**

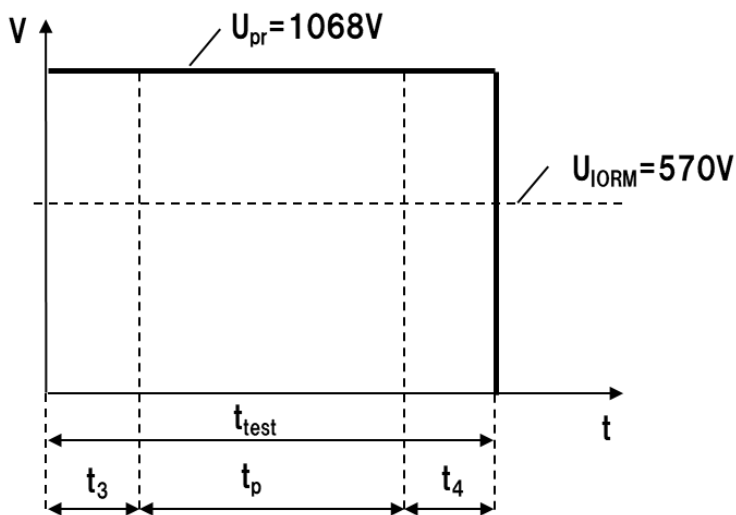


**Method a) Destructive Test, Type and Sample Test**



$t_1, t_2 = 1$  to  $10$  sec  
 $t_3, t_4 = 1$  sec  
 $t_m$  (PARTIAL DISCHARGE) =  $10$  sec  
 $t_{test} = 12$  sec  
 $t_{ini} = 60$  sec

**Method b) Non-destructive Test, 100% Production Test**



$t_3, t_4 = 0.1$  sec  
 $t_p$  (PARTIAL DISCHARGE) =  $1.0$  sec  
 $t_{test} = 1.2$  sec

<b>Caution</b>	GaAs Products	<p>This product uses gallium arsenide (GaAs). GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points.</p> <ul style="list-style-type: none"><li>• Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below.<ol style="list-style-type: none"><li>1. Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials.</li><li>2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal.</li></ol></li><li>• Do not burn, destroy, cut, crush, or chemically dissolve the product.</li><li>• Do not lick the product or in any way allow it to enter the mouth.</li></ul>
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